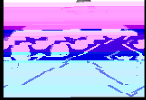
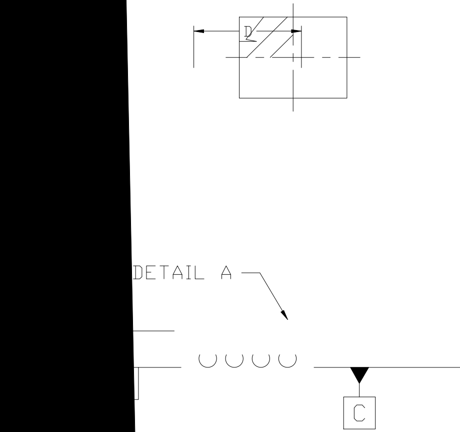


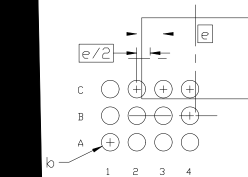
WLCSP12 1.62x1.22x0.539
CASE 499BJ
ISSUE D

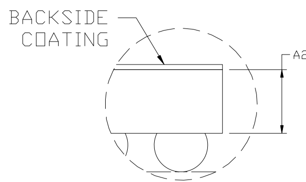
DATE 02 JUN 2022

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DIMENSION b IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER PARALLEL TO DATUM C.
4. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. DATUM C, THE SEATING PLANE, IS DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

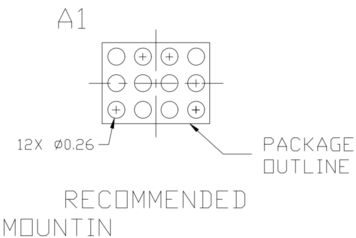






DETAIL A
SCALE 1:3

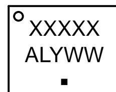
		MAX.
		0.594
		0.224
0.295	0.320	0.345
		0.299



RECOMMENDED
MOUNTIN

* For additional infol, SOLDERRM/D.

GENERIC
RKING DIAGRAM*



X = Specific Device Code
= Assembly Location
= Wafer Lot
= Year
= Work Week
= Pb−Free Package

tion is generic. Please refer to sheet for actual part marking. icator, “G” or microdot “▪”, may e present. Some products may e Generic Marking.